

*b1  
b7c*

a heat slug providing the die mount area, wherein said heat slug is attached under the lead frame with tape.

2. (twice amended) The strapless lead frame according to Claim 1, wherein the semiconductor die has four sides and corners, and the lead frame leads are all evenly distributed on each of the four sides and around the corners.

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5. (twice amended) A strapless lead frame for use with heat slug packages, comprising:

*b2*  
lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area; and

a heat slug providing a rectangular die mount area, wherein said heat slug is attached under the lead frame with tape, there being the same number of lead frame leads on opposite sides of the lead frame and a different number of lead frame leads on adjacent sides of the lead frame.

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## REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-6 are pending in this case. Claims 1, 2, 5 have been amended herein.

Claims 1-6 were finally rejected under 35 U.S.C. 102(b) as being anticipated by Ootsuki, et al. (U.S. 5,652,461). Claims 1 and 5, as amended herein, include the feature of "lead frame leads, all of said leads being evenly distributed around a semiconductor die mount area." Ootsuki does not teach or suggest such a feature. For example, in Figure 2B, Ootsuki's lead frame leads 1